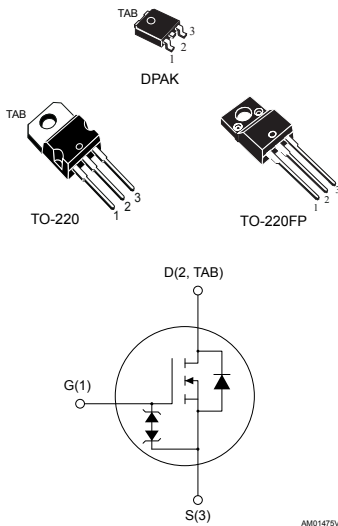


## N-channel 600 V, 1.2 $\Omega$ typ., 5 A SuperMESH™ Power MOSFET in DPAK, TO-220 and TO-220FP packages



### Features

Order codes	$V_{DS}$ @ $T_{jmax.}$	$R_{DS(on)}$ max.	Package
STD5NK60ZT4	650 V	1.6 $\Omega$	DPAK
STP5NK60Z			TO-220
STP5NK60ZFP			TO-220FP

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

### Applications

- Switching applications

### Description

These high-voltage devices are Zener-protected N-channel Power MOSFETs developed using the SuperMESH™ technology by STMicroelectronics, an optimization of the well-established PowerMESH™. In addition to a significant reduction in on-resistance, these devices are designed to ensure a high level of dv/dt capability for the most demanding applications.

#### Product status link

[STD4NK60ZT4](#)
[STP5NK60Z](#)
[STP5NK60ZFP](#)

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		DPAK, TO-220	TO-220FP	
$V_{DS}$	Drain-source voltage	600		V
$V_{GS}$	Gate-source voltage	±30		V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	5	5 <sup>(1)</sup>	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ °C}$	3.16	3.16 <sup>(1)</sup>	A
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	20	20 <sup>(1)</sup>	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ °C}$	90	25	W
ESD	Gate-source human body model ( $R = 1.5\text{ k}\Omega$ , $C = 100\text{ pF}$ )	3		kV
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat-sink ( $t = 1\text{ s}$ , $T_C = 25\text{ °C}$ )		2.5	kV
$dv/dt$ <sup>(3)</sup>	Peak diode recovery voltage slope	4.5		V/ns
$T_j$	Operating junction temperature range	-55 to 150		°C
$T_{stg}$	Storage temperature range			

1. Limited by maximum junction temperature.

2. Pulse width limited by safe operating area.

3.  $I_{SD} \leq 5\text{ A}$ ,  $di/dt \leq 200\text{ A}/\mu\text{s}$ ,  $V_{DSpeak} \leq V_{(BR)DSS}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value			Unit
		DPAK	TO-220	TO-220FP	
$R_{thj-case}$	Thermal resistance junction-case	1.39		5	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient		62.5		°C/W
$R_{thj-pcb}$ <sup>(1)</sup>	Thermal resistance junction-pcb	50			°C/W

1. When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_j$ Max)	5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ °C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	220	mJ

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 50\text{ }\mu\text{A}$	3	3.75	4.5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 2.5\text{ A}$		1.2	1.6	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	690		$\mu\text{F}$
$C_{oss}$	Output capacitance			90		
$C_{rss}$	Reverse transfer capacitance			20		
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }480\text{ V}$ , $V_{GS} = 0\text{ V}$	-	40		$\mu\text{F}$
$Q_g$	Total gate charge	$V_{DD} = 400\text{ V}$ , $I_D = 5\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 16. Test circuit for gate charge behavior)	-	26	34	nC
$Q_{gs}$	Gate-source charge			6		
$Q_{gd}$	Gate-drain charge			14		

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 2.5\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	16		ns
$t_r$	Rise time			25		
$t_{d(off)}$	Turn-off delay time	(see Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	36		ns
$t_f$	Fall time			25		
$t_{r(voff)}$	Off-voltage rise time	$V_{DD} = 480\text{ V}$ , $I_D = 5\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	12		ns
$t_f$	Fall time			10		
$t_c$	Cross-over time	(see Figure 17. Test circuit for inductive load switching and diode recovery times and Figure 20. Switching time waveform)		24		ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				20	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5\text{ A}$ , $V_{GS} = 0\text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$	-	485		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 30\text{ V}$ (see <a href="#">Figure 17. Test circuit for inductive load switching and diode recovery times</a> )		2.7		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			11		A

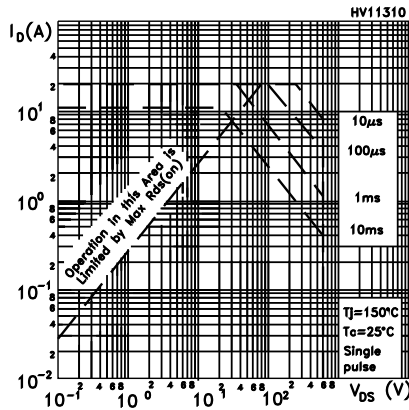
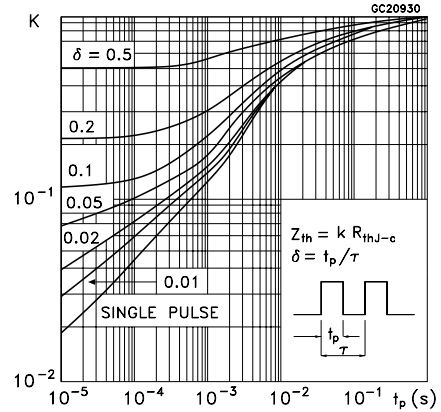
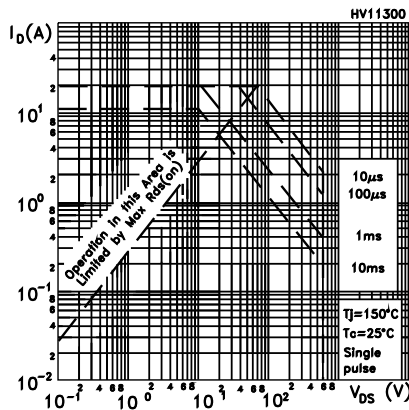
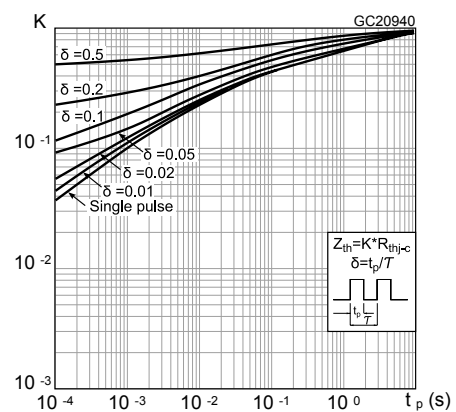
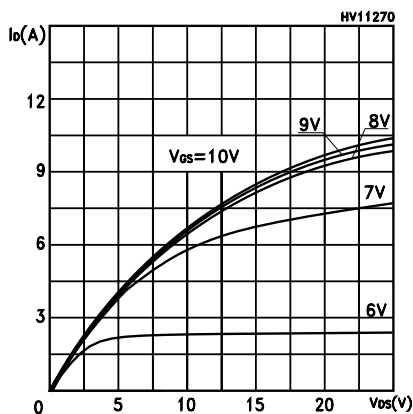
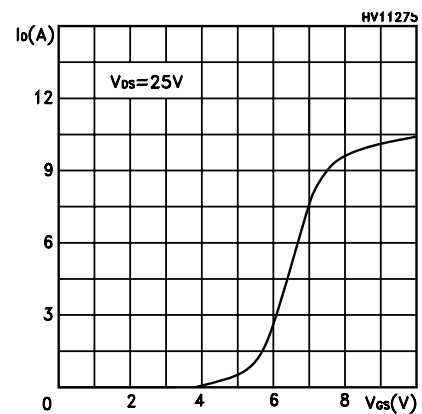
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

**Table 8. Gate-Source Zener Diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1\text{ mA}$ , $I_D = 0\text{ A}$	30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

## 2.1 Electrical characteristics curves

**Figure 1. Safe operating area for DPAK and TO-220**

**Figure 2. Thermal impedance for DPAK and TO-220**

**Figure 3. Safe operating area for TO-220FP**

**Figure 4. Thermal impedance for TO-220FP**

**Figure 5. Output characteristics**

**Figure 6. Transfer characteristics**


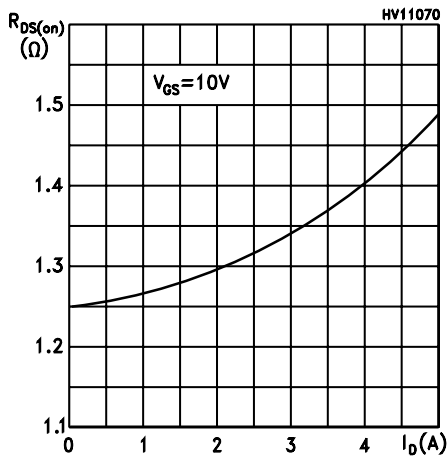
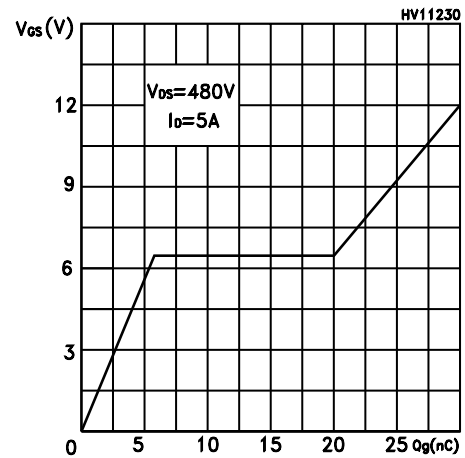
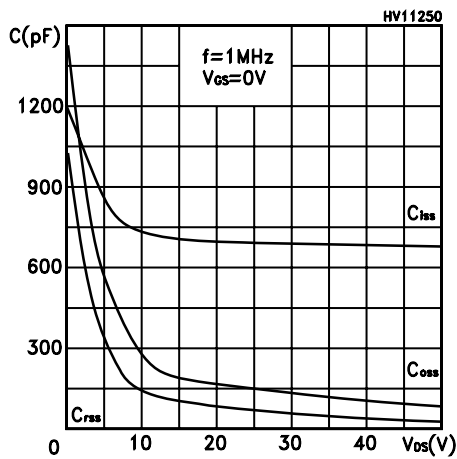
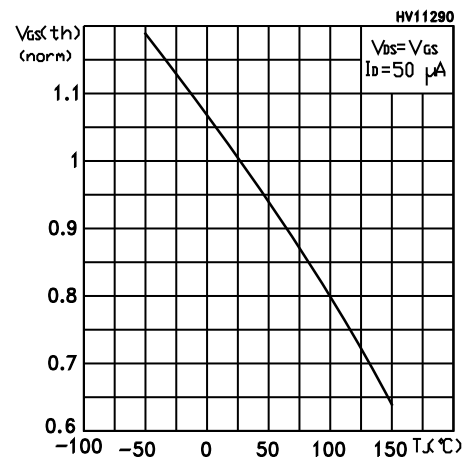
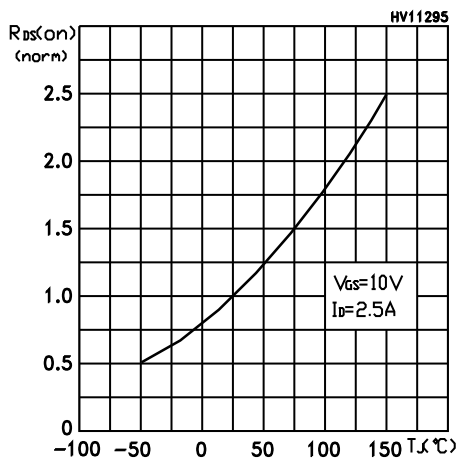
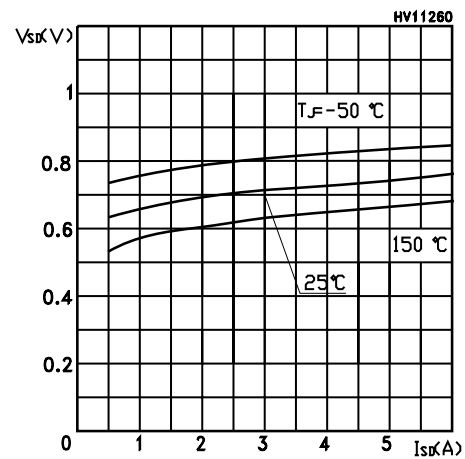
**Figure 7. Static drain-source on resistance**

**Figure 8. Gate charge vs gate-source voltage**

**Figure 9. Capacitance variations**

**Figure 10. Normalized gate threshold voltage vs temperature**

**Figure 11. Normalized on resistance vs temperature**

**Figure 12. Source-drain diode forward characteristic**


Figure 13. Normalized  $V_{(BR)DSS}$  vs temperature

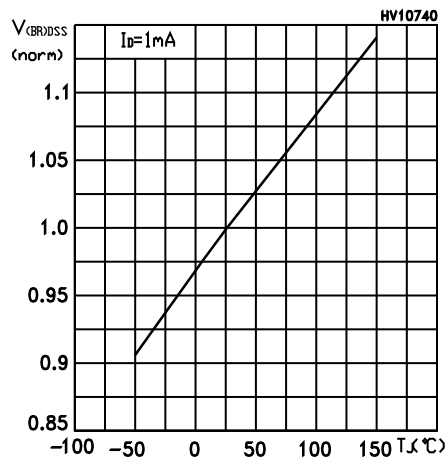
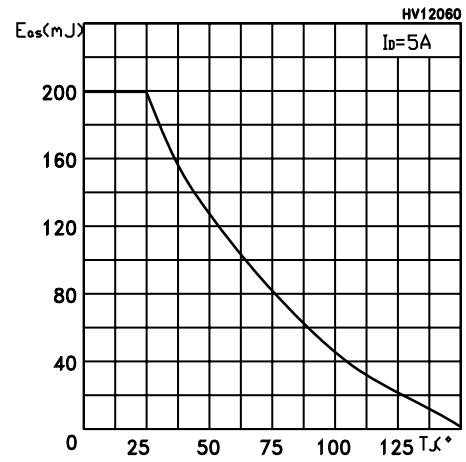
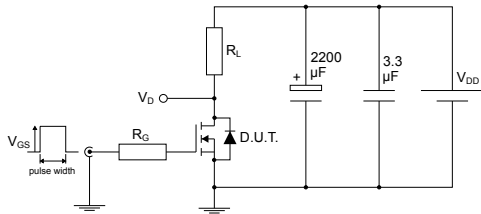


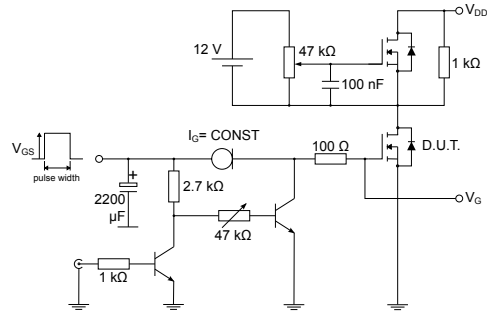
Figure 14. Maximum avalanche energy vs temperature



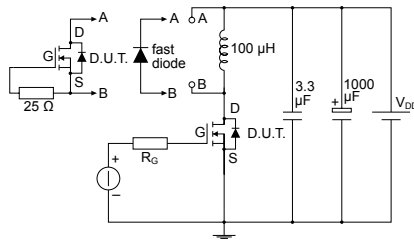
### 3 Test circuits

**Figure 15. Test circuit for resistive load switching times**


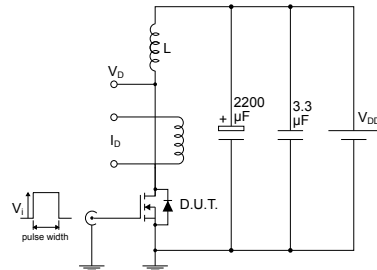
AM01468v1

**Figure 16. Test circuit for gate charge behavior**


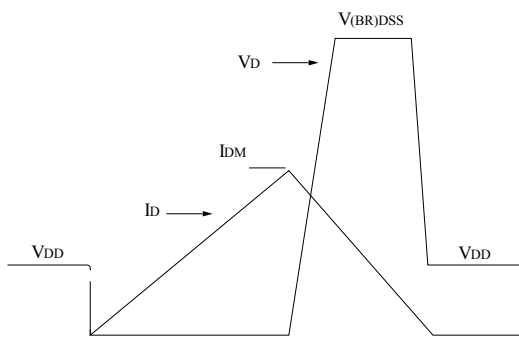
AM01469v1

**Figure 17. Test circuit for inductive load switching and diode recovery times**


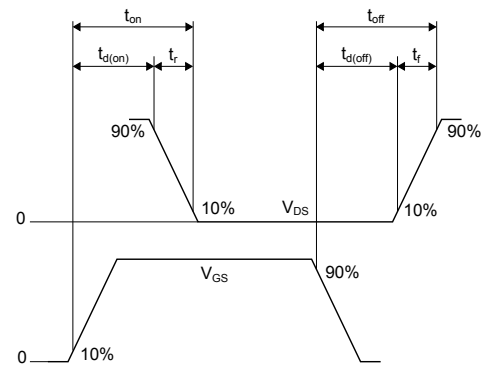
AM01470v1

**Figure 18. Unclamped inductive load test circuit**


AM01471v1

**Figure 19. Unclamped inductive waveform**


AM01472v1

**Figure 20. Switching time waveform**


AM01473v1



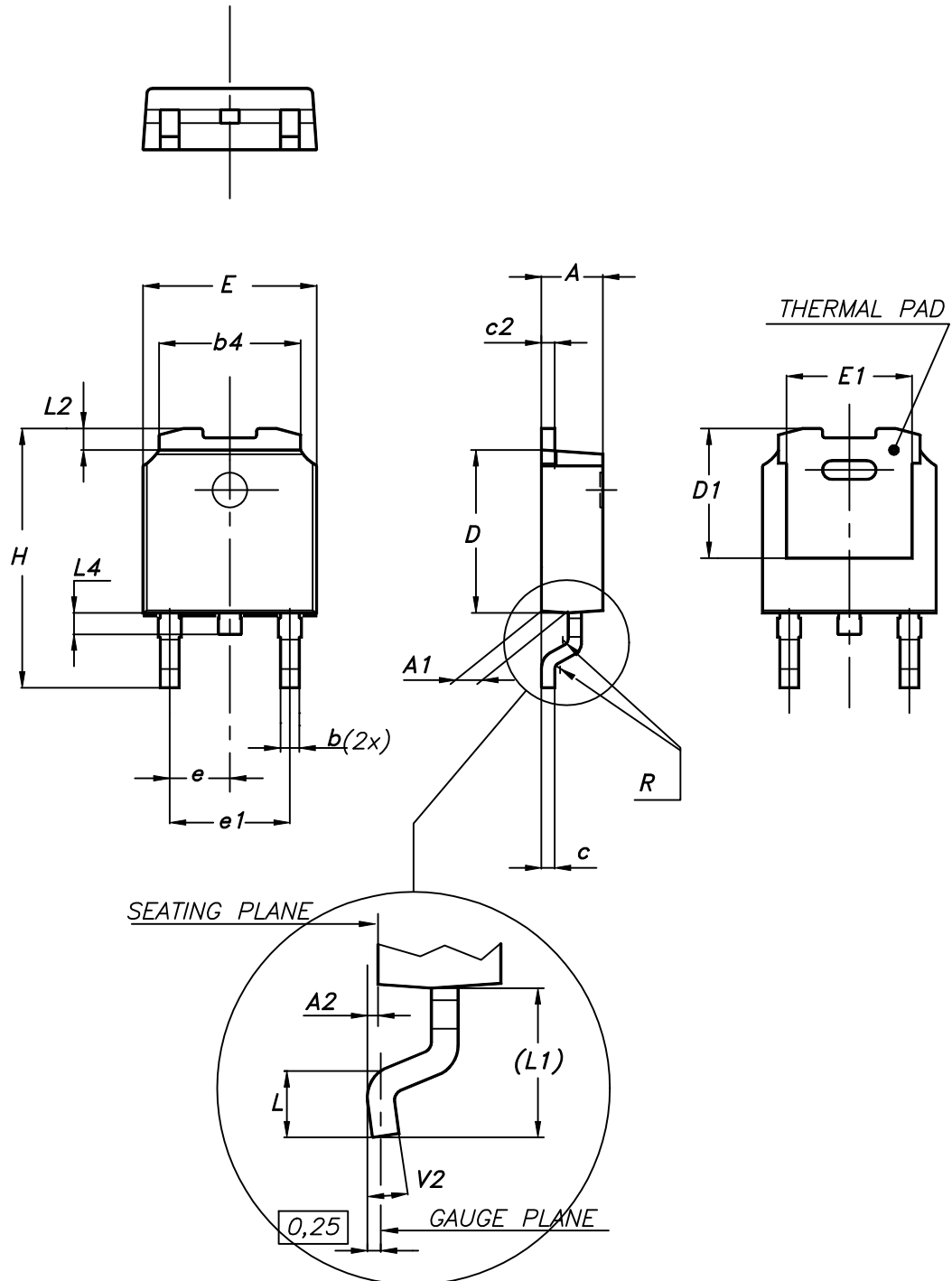
## 4 Package information

---

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 DPAK (TO-252) type A2 package information

Figure 21. DPAK (TO-252) type A2 package outline



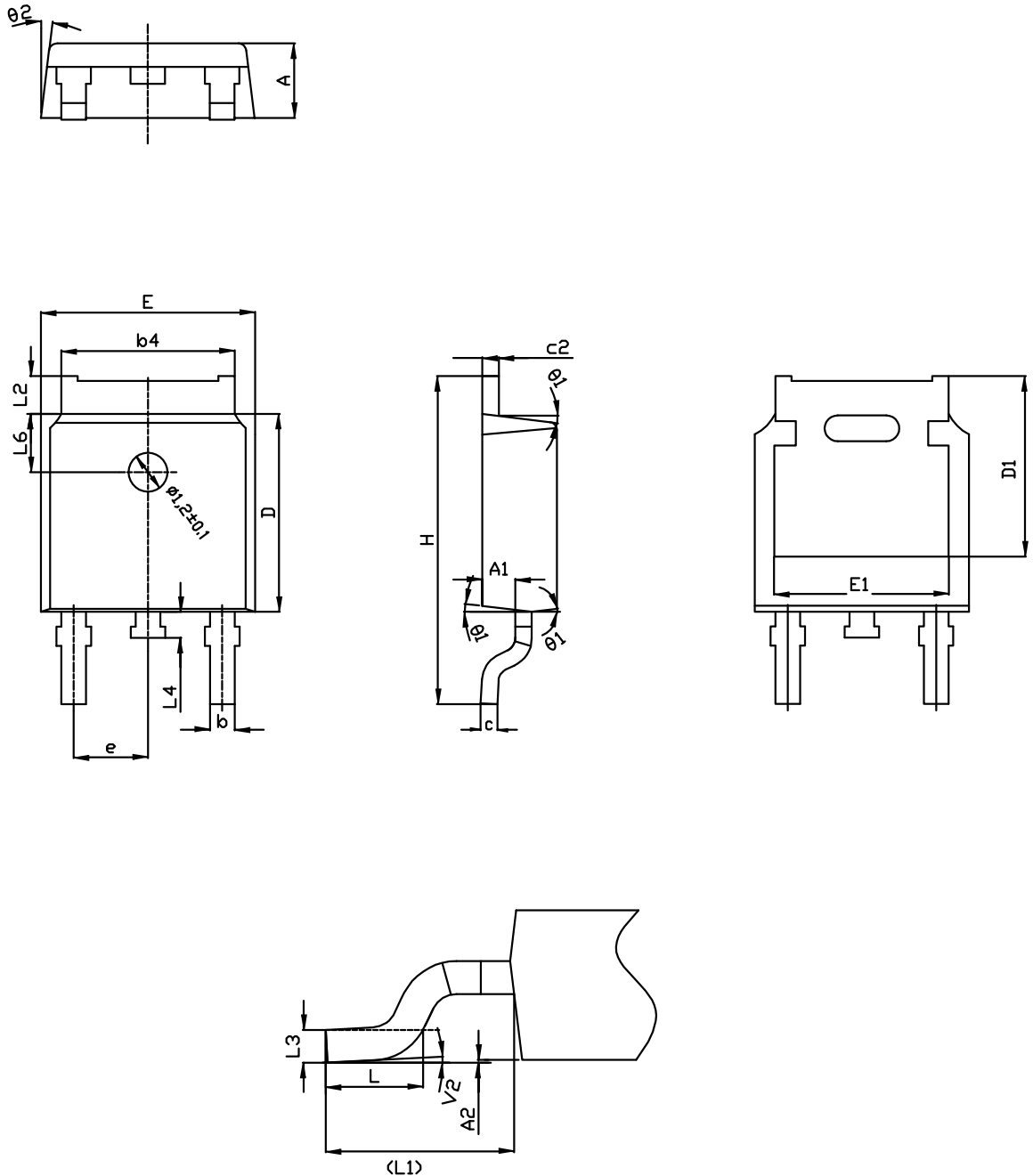
0068772\_type-A2\_rev25

**Table 9. DPAK (TO-252) type A2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

## 4.2 DPAK (TO-252) type C2 package information

Figure 22. DPAK (TO-252) type C2 package outline

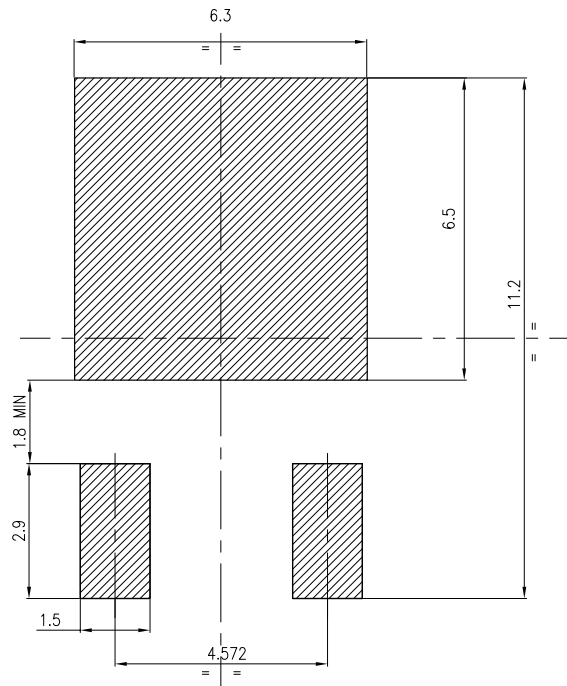


0068772\_C2\_25

**Table 10. DPAK (TO-252) type C2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

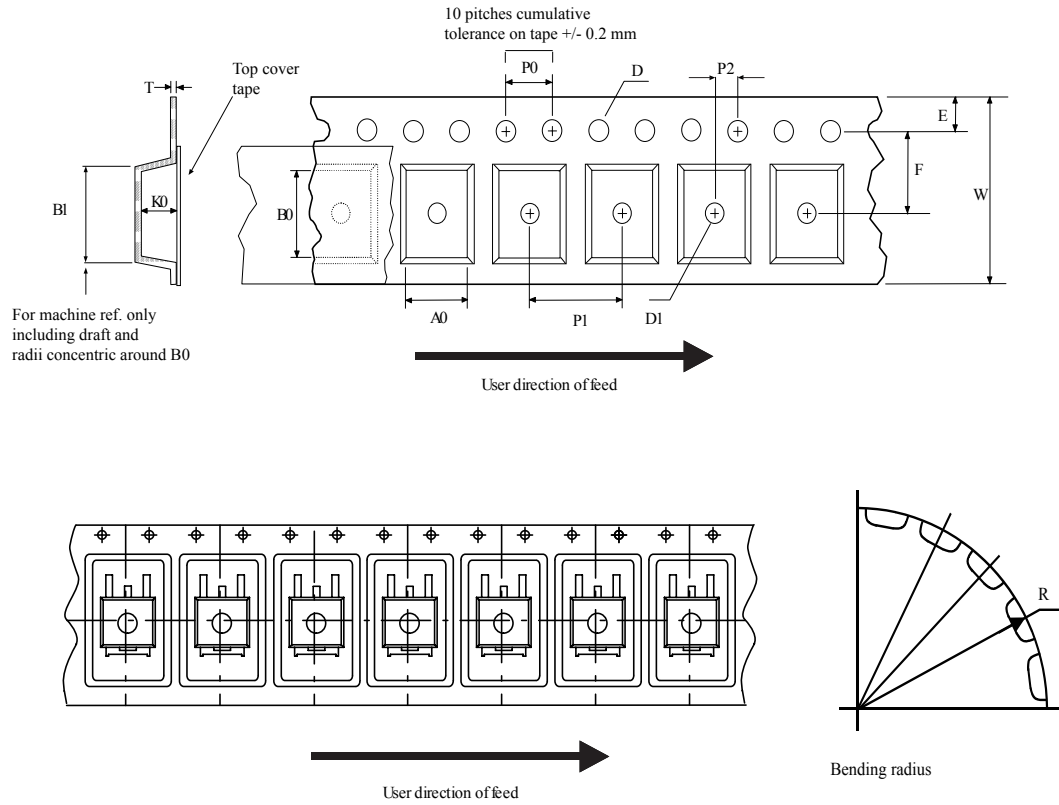
Figure 23. DPAK (TO-252) recommended footprint (dimensions are in mm)



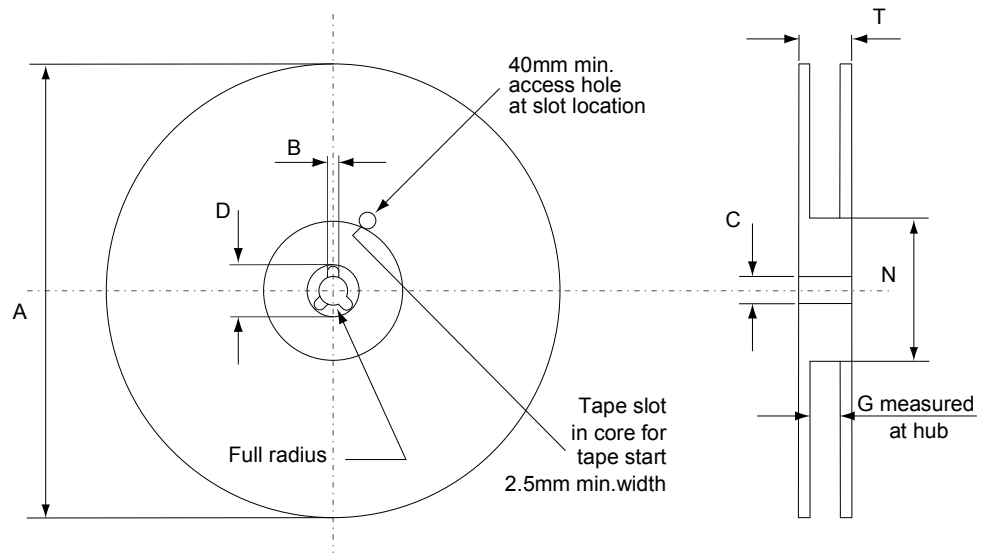
FP\_0068772\_25

### 4.3 DPAK (TO-252) packing information

Figure 24. DPAK (TO-252) tape outline



AM08852v1

**Figure 25. DPAK (TO-252) reel outline**


AM06038v1

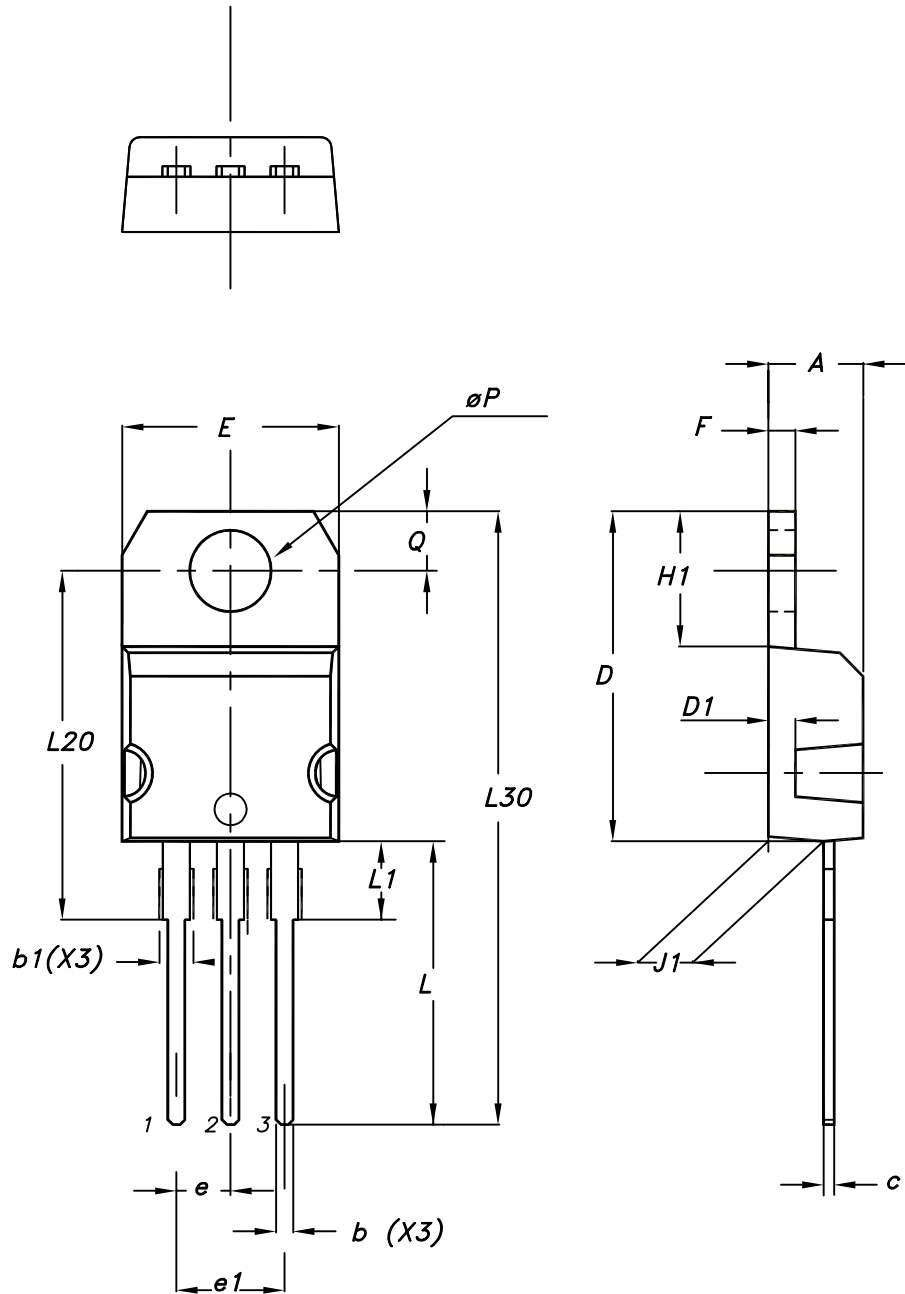
**Table 11. DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			



#### 4.4 TO-220 type A package information

Figure 26. TO-220 type A package outline



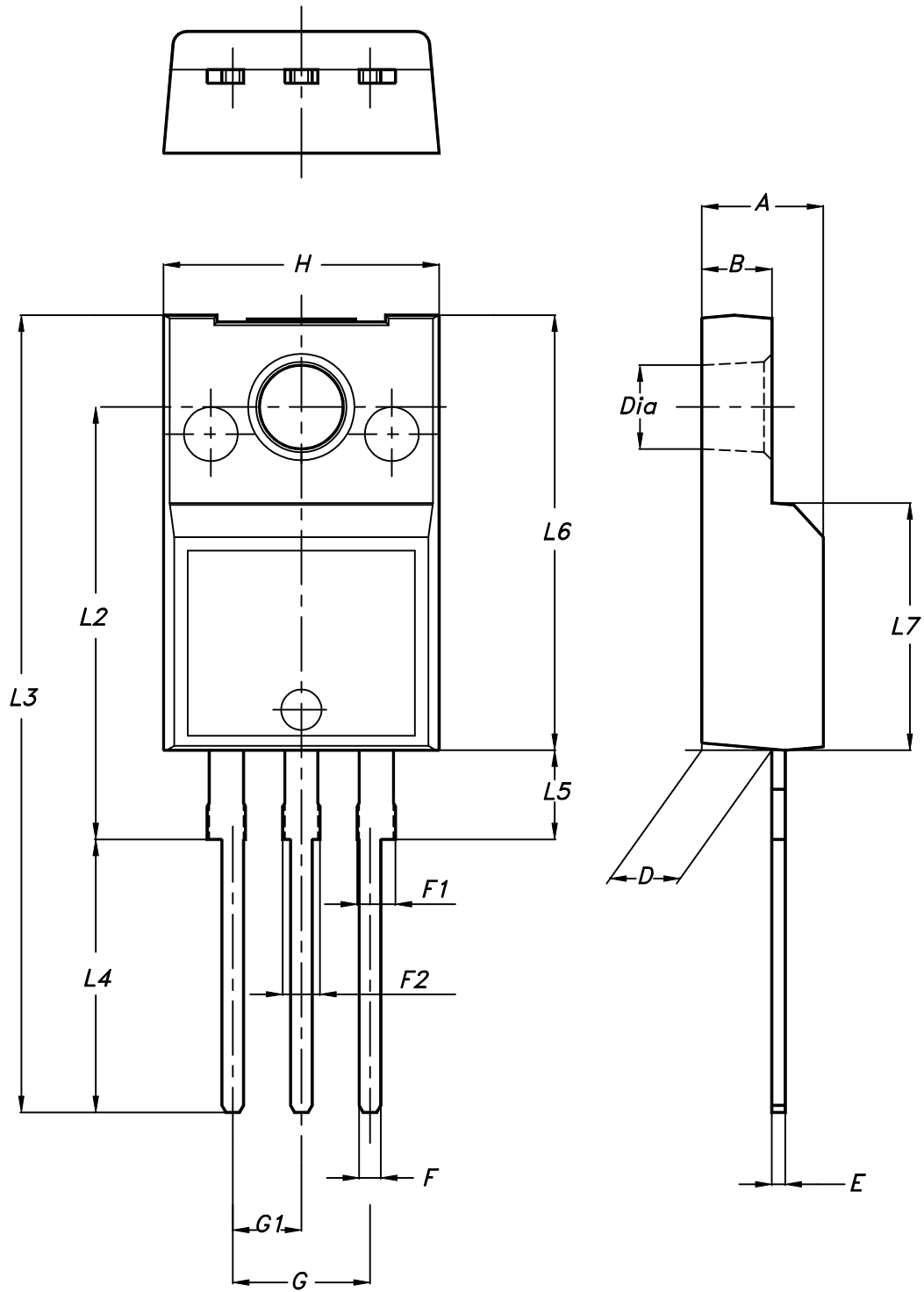
0015988\_typeA\_Rev\_21

**Table 12. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

### 4.5 TO-220FP package information

Figure 27. TO-220FP package outline



7012510\_Rev\_12\_B

**Table 13. TO-220FP package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

## 5 Ordering information

Table 14. Order codes

Order code	Marking	Package	Packing
STD5NK60ZT4	D5NK60Z	DPAK	Tape and reel
STP5NK60Z	P5NK60Z	TO-220	Tube
STP5NK60ZFP	P5NK60ZFP	TO-220FP	Tube

## Revision history

**Table 15. Document revision history**

Date	Version	Changes
05-Apr-2005	1	First issue
29-Apr-2005	2	Modified value in Table 7.
06-Sep-2005	3	Inserted Ecopack indication
14-Oct-2005	4	Modified value on Table 1
28-Oct-2005	5	Tape & Reel info added
14-Nov-2005	6	Modified value on Table 6
15-Dec-2005	7	Various corrections
22-Aug-2018	8	Removed maturity status indication from cover page. The document status is production data. Updated <a href="#">Section 4 Package information</a> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings</b> .....	<b>2</b>
<b>2</b>	<b>Electrical characteristics</b> .....	<b>3</b>
<b>2.1</b>	Electrical characteristics curves .....	5
<b>3</b>	<b>Test circuits</b> .....	<b>8</b>
<b>4</b>	<b>Package information</b> .....	<b>9</b>
<b>4.1</b>	DPAK (TO-252) type A2 package information .....	9
<b>4.2</b>	DPAK (TO-252) type C2 package information .....	11
<b>4.3</b>	DPAK (TO-252) packing information .....	14
<b>4.4</b>	TO-220 type A package information .....	16
<b>4.5</b>	TO-220FP package information .....	18
<b>5</b>	<b>Ordering information</b> .....	<b>21</b>
	<b>Revision history</b> .....	<b>22</b>

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved